SCLS417H - JUNE 1998 - REVISED SEPTEMBER 2003

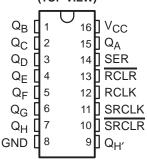
- Inputs Are TTL-Voltage Compatible
- 8-Bit Serial-In, Parallel-Out Shift Registers With Storage
- Independent Direct Overriding Clears on Shift and Storage Registers
- Independent Clocks for Both Shift and Storage Registers
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

description/ordering information

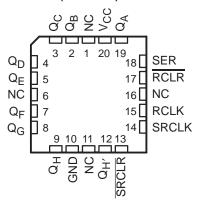
The 'AHCT594 devices contain an 8-bit serial-in, parallel-out shift register that feeds an 8-bit D-type storage register. Separate clocks and direct overriding clear (\overline{SRCLR} , \overline{RCLR}) inputs are provided on both the shift and storage registers. A serial ($Q_{H'}$) output is provided for cascading purposes.

Both the shift register (SRCLK) and storage register (RCLK) clocks are positive edge triggered. If both clocks are connected together, the shift register always is one count pulse ahead of the storage register.

SN54AHCT594 . . . J OR W PACKAGE SN74AHCT594 . . . D, DB, N, NS, OR PW PACKAGE (TOP VIEW)



SN54AHCT594 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

ORDERING INFORMATION

TA	PACK	AGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	PDIP – N	Tube	SN74AHCT594N	SN74AHCT594N	
	2010 5	Tube	SN74AHCT594D	ALIOTEO	
	SOIC - D	Tape and reel	SN74AHCT594DR	AHCT594	
-40°C to 85°C	SOP – NS Tape and reel		SN74AHCT594NSR	AHCT594	
	SSOP – DB Tape and reel SN74AHCT594DBR		SN74AHCT594DBR	HB594	
	TOOOD DW	Tube	SN74AHCT594PW	LIDEO4	
	TSSOP – PW	Tape and reel	SN74AHCT594PWR	HB594	
	CDIP – J	Tube	SNJ54AHCT594J	SNJ54AHCT594J	
–55°C to 125°C	CFP – W	Tube	SNJ54AHCT594W	SNJ54AHCT594W	
	LCCC – FK	Tube	SNJ54AHCT594FK	SNJ54AHCT594FK	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



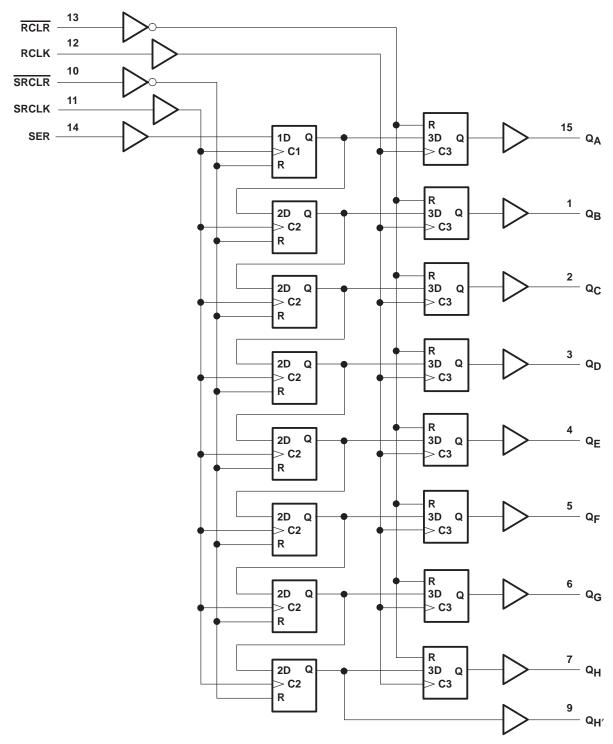
SN54AHCT594, SN74AHCT594 8-BIT SHIFT REGISTERS WITH OUTPUT REGISTERS SCLS417H – JUNE 1998 – REVISED SEPTEMBER 2003

FUNCTION TABLE

		INPUTS			FUNCTION
SER	SRCLK	SRCLR	RCLK	RCLR	FUNCTION
Х	Х	L	Х	Χ	Shift register is cleared.
L	1	Н	Х	Х	First stage of shift register goes low. Other stages store the data of previous stage, respectively.
Н	1	Н	Х	Х	First stage of shift register goes high. Other stages store the data of previous stage, respectively.
L	\downarrow	Н	Х	Χ	Shift-register state is not changed.
Х	Χ	Χ	X	L	Storage register is cleared.
Х	Χ	X	\uparrow	Н	Shift-register data is stored in the storage register.
Х	X	X	\downarrow	Н	Storage-register state is not changed.



logic diagram (positive logic)

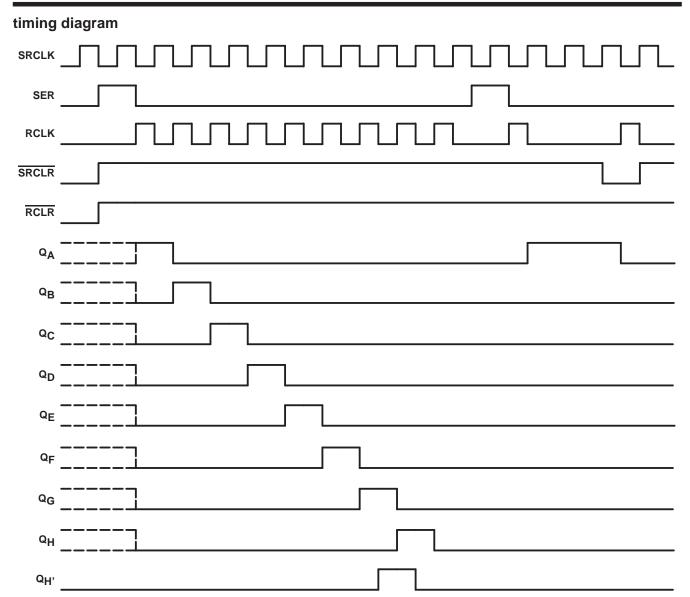


Pin numbers shown are for the D, DB, J, N, NS, PW, and W packages.



SN54AHCT594, SN74AHCT594 8-BIT SHIFT REGISTERS WITH OUTPUT REGISTERS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		–0.5 V to 7 V
Input voltage range, V _I (see Note 1)		–0.5 V to 7 V
Output voltage range, VO (see Note 1)		$0.5 V$ to $V_{CC} + 0.5 V$
Input clamp current, I_{IK} ($V_I < 0$)		–20 mA
Output clamp current, IOK (VO < 0 or VO > VCO	s)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})		±25 mA
Continuous current through V _{CC} or GND		±75 mA
Package thermal impedance, θ_{JA} (see Note 2):	D package	73°C/W
-	DB package	82°C/W
	N package	67°C/W
	NS package	64°C/W
	PW package	108°C/W
Storage temperature range, T _{sta}		65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		SN54AHCT594		SN74AH	CT594	
		MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2	3	2		V
V _{IL}	Low-level input voltage		0.8		0.8	V
VI	Input voltage	0	5.5	0	5.5	V
Vo	Output voltage	0/	VCC	0	VCC	V
IOH	High-level output current	272	-8		-8	mA
loL	Low-level output current	70 ₂	8		8	mA
Δt/Δν	Input transition rise or fall rate	Q	20		20	ns/V
T _A	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

SN54AHCT594, SN74AHCT594 8-BIT SHIFT REGISTERS WITH OUTPUT REGISTERS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

242445	TEGT CONDITIONS	Voc	T _A = 25°C			SN54AHCT594		SN74AHCT594			
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
V	I _{OH} = -50 μA	45.1/	4.4	4.5		4.4		4.4		V	
VOH	I _{OH} = -8 mA	4.5 V	3.94			3.8	3	3.8		V	
V/	I _{OL} = 50 μA	45.1/			0.1		0.1		0.1	V	
VoL	I _{OL} = 8 mA	4.5 V			0.36	4	0.44		0.44	V	
lį	V _I = 5.5 V or GND	0 V to 5.5 V			±0.1	1	±1*		±1	μΑ	
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			2	2	20		20	μΑ	
ΔI _{CC} †	One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V			2	PRO	2.2		2.2	mA	
Ci	V _I = V _{CC} or GND	5 V		2	10				10	pF	

 $^{^{\}star}$ On products compliant to MIL-PRF-38535, this parameter is not production tested at V_{CC} = 0 V.

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

			T _A = 2	25°C	SN54AH	CT594	SN74AH	CT594	
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
	Dulas dimetias	RCLK or SRCLK high or low	5		5.5		5.5		
t _W	Pulse duration	RCLR or SRCLR low	5.2		5.5	14	5.5		ns
		SER before SRCLK↑	3		3	J. J.	3		
		SRCLK↑ before RCLK↑‡	5		5.0		5		
t _{su}	Setup time	SRCLR low before RCLK↑	5		5		5		ns
		SRCLR high (inactive) before SRCLK↑			3.3		3.3		
		RCLR high (inactive) before RCLK↑	3.4		3.8		3.8		
th	Hold time	SER after SRCLK↑	2		2		2		ns

[‡] This setup time allows the storage register to receive stable data from the shift register. The clocks can be tied together, in which case the shift register is one clock pulse ahead of the storage register.

[†] This is the increase in supply current for each input at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

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switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

	FROM	то	LOAD	T,	ղ = 25°C	;	SN54AH	CT594	SN74AH	CT594			
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT		
			C _L = 15 pF	135*	170*		115*		115		N 41 1-		
f _{max}			C _L = 50 pF	120	140		95		95		MHz		
t _{PLH}	DOL K	0 0	0. 45 = 5		3.3*	6.2*	1*	6.5*	1	6.5			
t _{PHL}	RCLK	Q_A-Q_H	C _L = 15 pF		3.7*	6.5*	1*	6.9*	1	6.9	ns		
t _{PLH}	ODOLK		0 45 5		3.7*	6.8*	1*	7.2*	1	7.2			
t _{PHL}	SRCLK	$Q_{H'}$	QH'	QH'	C _L = 15 pF		4.1*	7.2*	1*	7.6*	1	7.6	ns
t _{PHL}	RCLR	Q _A -Q _H	C _L = 15 pF		4.5*	7.6*	1*,	8.2*	1	8.2	ns		
t _{PHL}	SRCLR	Q _H ′	C _L = 15 pF		4.1*	7.1*	250	7.6*	1	7.6	ns		
^t PLH	50114	0 0	0 50 5		4.9	7.8	O 1	8.3	1	8.3			
t _{PHL}	RCLK	Q_A – Q_H	C _L = 50 pF		5.8	8.9	Q 1	9.7	1	9.7	ns		
t _{PLH}	ODOLK		0 50 5		5.5	8.6	1	9.1	1	9.1			
t _{PHL}	SRCLK	Q _H ′	$C_L = 50 pF$		6	9.2	1	10.1	1	10.1	ns		
t _{PHL}	RCLR	Q_A-Q_H	C _L = 50 pF		6.6	10	1	10.7	1	10.7	ns		
t _{PHL}	SRCLR	Q _H ′	C _L = 50 pF		6	9.2	1	10.1	1	10.1	ns		

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics, $V_{CC} = 5 \text{ V}$, $C_L = 50 \text{ pF}$, $T_A = 25^{\circ}\text{C}$ (see Note 4)

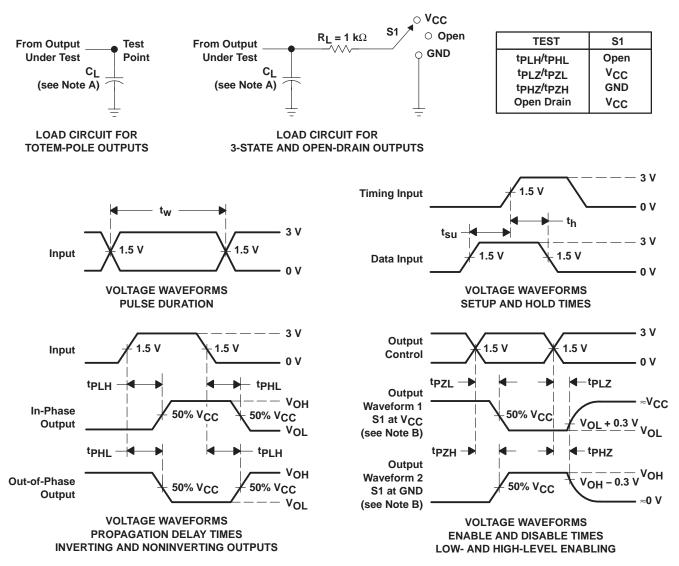
	DADAMETED	SN7			
	PARAMETER				UNIT
VOL(P)	Quiet output, maximum dynamic VOL		1		V
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}		-0.6		V
V _{OH(V)}	Quiet output, minimum dynamic V _{OH}		3.8		V
V _{IH(D)}	High-level dynamic input voltage	2			V
V _{IL(D)}	Low-level dynamic input voltage			0.8	V

NOTE 4: Characteristics are for surface-mount packages only.

operating characteristics, V_{CC} = 5 V, T_A = 25°C

	PARAMETER		ONDITIONS	TYP	UNIT
ſ	C _{pd} Power dissipation capacitance	No load,	f = 1 MHz	112	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_Q = 50 \Omega$, $t_f \leq 3$ ns, $t_f \leq 3$ ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms









PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74AHCT594D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT594DBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT594DBRE4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT594DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT594DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT594DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT594N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AHCT594NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AHCT594NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT594NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT594PW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT594PWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT594PWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT594PWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is



PACKAGE OPTION ADDENDUM

12-Jan-2006

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N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



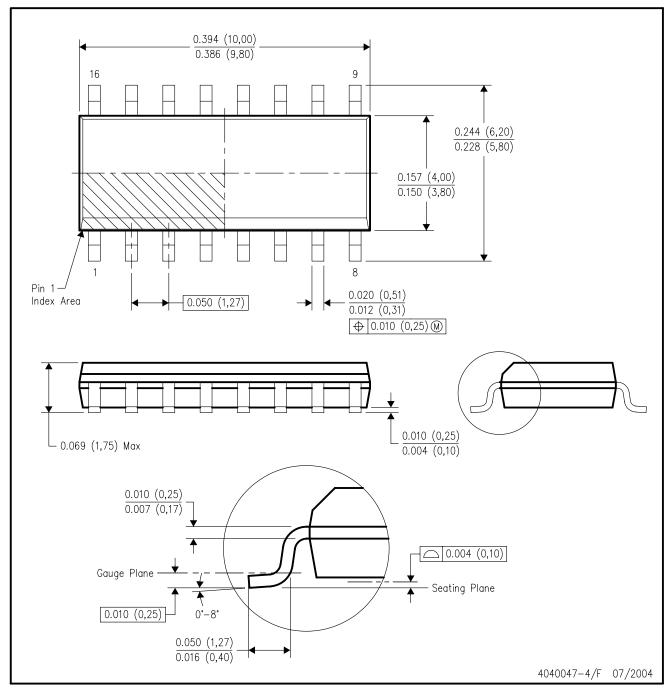
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AC.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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